This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended): A magnetic head, comprising:

a substrate;

a read head being fabricated upon said substrate;

a P1 pole being fabricated upon said read head;

an insulation layer being fabricated upon said P1 pole;

a P2 pole tip seed layer being fabricated upon portions of said insulation layer;

a dielectric material layer being fabricated upon said P2 pole tip seed layer and upon said insulation layer;

a P2 pole tip being fabricated upon said P2 pole tip seed layer and within said dielectric material layer;

a back gap piece being fabricated within said dielectric material layer and in magnetic interconnection with said P1 pole;

an induction coil seed layer being fabricated in part upon said insulation layer and in part upon portions of said dielectric material layer;

an induction coil being fabricated upon said induction coil seed layer and within said dielectric material layer;

a second insulation layer being fabricated upon said induction coil;

a P2 pole yoke being fabricated upon said second insulation layer in magnetic interconnection with said P2 pole tip and with said back gap piece;

an encapsulation layer being fabricated above said P2 pole yoke.

2. (original): A magnetic head as described in claim 1 wherein said dielectric material layer includes a P2 pole tip trench, an induction coil trench and a back gap piece trench.

3. (currently amended): A magnetic head as described in claim 2 wherein said ~~P1~~ P2 pole tip trench, said induction coil trench and said back gap piece trench are formed in a single reactive ion etch fabrication step.

4. (original): A magnetic head as described in claim 3 wherein a P1 pole notch is formed in said P1 pole proximate said P2 pole tip.

5. (original): A magnetic head as described in claim 4 wherein a P1 pole notching trench is fabricated in said dielectric material layer in a second reactive ion etch fabrication step.

6. (currently amended): A hard disk drive comprising:

at least one hard disk being fabricated for rotary motion upon a disk drive;

at least one magnetic head adapted to fly over said hard disk for writing data on said hard disk, said magnetic head including:

a substrate;

a read head being fabricated upon said substrate;

a P1 pole being fabricated upon said read head;

an insulation layer being fabricated upon said P1 pole;

a P2 pole tip seed layer being fabricated upon portions of said insulation layer;

a dielectric material layer being fabricated upon said P2 pole tip seed layer and upon said insulation layer;

a P2 pole tip being fabricated upon said P2 pole tip seed layer and within said dielectric material layer;

a back gap piece being fabricated within said dielectric material layer and in magnetic interconnection with said P1 pole;

an induction coil seed layer being fabricated in part upon said insulation layer and in part upon portions of said dielectric material layer;

an induction coil being fabricated upon said induction coil seed layer and within said dielectric material layer;

a second insulation layer being fabricated upon said induction coil;

a P2 pole yoke being fabricated upon said second insulation layer in magnetic interconnection with said P2 pole tip and with said back gap piece;

an encapsulation layer being fabricated above said P2 pole yoke.

7. (original): A hard disk drive as described in claim 6 wherein said dielectric material layer includes a P2 pole tip trench, an induction coil trench and a back gap piece trench.

8. (currently amended): A hard disk drive as described in claim 7 wherein said ~~P1~~ P2 pole tip trench, said induction coil trench and said back gap trench are formed in a single reactive ion etch fabrication step.

9. (original): A hard disk drive as described in claim 8 wherein a P1 pole notch is formed in said P1 pole proximate said P2 pole tip.

10. (withdrawn): A method for fabricating a magnetic head comprising the steps of:

fabricating a read head upon a substrate;

fabricating a P1 pole upon said read head;

fabricating an insulation layer upon said P1 pole;

fabricating an RIE etchable dielectric material layer upon said insulation layer;

fabricating trenches within said dielectric material layer, including a P2 pole tip trench, an induction coil trench and a back gap piece trench;

simultaneously fabricating a P2 pole tip within said P2 pole tip trench and a back gap piece within said back gap piece trench, such that said back gap piece is magnetically interconnected with said P1 pole;

fabricating an induction coil within said induction coil trench;

fabricating a second insulation layer upon said induction coil;

fabricating a P2 pole yoke above said second insulation layer in magnetic interconnection with said P2 pole tip and said back gap piece;

fabricating an encapsulation layer above said P2 pole yoke.

11. (withdrawn): A method for fabricating a magnetic head as described in claim 10, further including the steps of fabricating a patterned P2 pole tip seed layer upon said insulation layer prior to fabricating said dielectric material layer.

12. (withdrawn): A method for fabricating a magnetic head as described in claim 11 wherein said P2 pole tip seed layer is not deposited in a location of said induction coil trench.

13. (withdrawn): A method for fabricating a magnetic head as described in claim 10 including the further step of depositing an induction coil seed layer within said induction coil trench, subsequent to fabricating said P2 pole tip and back gap piece.

14. (withdrawn): A method for fabricating a magnetic head as described in claim 10, wherein said step of fabricating trenches within said dielectric material layer is performed in a reactive ion etch process.

15. (withdrawn): A method for fabricating a magnetic head as described in claim 14 wherein said dielectric material layer is comprised of SIO_2 and said reactive ion etch process is conducted utilizing fluorine ion species.

16. (withdrawn): A method for fabricating a magnetic head as described in claim 14 wherein said dielectric material layer is comprised of an organic polymer material and said RIE etching process is conducted utilizing an oxygen ion species.

17. (withdrawn): A method for fabricating a magnetic head as described in claim 10 wherein a P1 pole notching process is conducted following the fabrication of said P2 pole yoke.

18. (withdrawn): A method for fabricating a magnetic head as described in claim 17 wherein said P1 pole notching step includes the steps of RIE etching said dielectric material proximate said P2 pole tip, and ion beam etching said P2 pole tip seed layer, said insulation layer and portions of said P1 pole.

19. (withdrawn): A method for fabricating a magnetic head as described in claim 13 wherein said P2 pole tip seed layer is comprised of NiFe, and said induction coil seed layer is composed of copper.